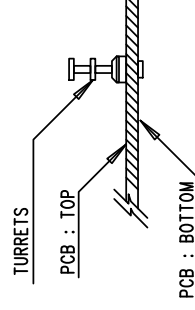
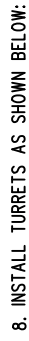




1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP
TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		 ANALOG DEVICES POWER BY  LINEAR™ FOR AOL CUSTOMER USE ONLY 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408) 432-1900 www.analog.com	
PCB DES.	HZ		
APP ENG.	Charlie		
		TITLE: TOP ASSEMBLY DRAWING 40V, 1.4A DUAL STEP-DOWN MODULE REGULATOR	
		SIZE	IC NO. LTM8078
		N/A	DEM0 CIRCUIT 2777A
		REV. 1	
SCALE = NONE		FILENAME: DC2777A.PCB SHT 1 OF 2	